

	<b>Title</b>	<b>Current OR</b>
<b>1</b>	<b>Apparatus and method for mounting electronic parts</b>	<b>29/832</b>
<b>2</b>	<b>Parts mounting method and parts mounting apparatus</b>	<b>29/832</b>
<b>3</b>	<b>Electronic part mounting machine</b>	<b>29/833</b>
<b>4</b>	<b>Connector manufacturing method</b>	<b>29/832</b>
<b>5</b>	<b>Method of mounting parts</b>	<b>29/836</b>
<b>6</b>	<b>Method and apparatus for mounting electronic part</b>	<b>29/832</b>
<b>7</b>	<b>Apparatus for and method of mounting electronic parts</b>	<b>29/832</b>
<b>8</b>	<b>Electronic parts mounting method</b>	<b>29/840</b>
<b>9</b>	<b>Method and apparatus for mounting parts with pick-up mistake detection and storage of mistake rate</b>	<b>29/833</b>

	<b>Current XRef</b>	<b>Retrieval Classif</b>
<b>1</b>	<b>29/740; 29/743; 29/833</b>	<b>29/832</b>
<b>2</b>	<b>29/740; 29/743</b>	<b>29/832</b>
<b>3</b>	<b>29/740; 29/832</b>	<b>29/832</b>
<b>4</b>	<b>29/743; 294/64.1; 414/737; 901/40</b>	<b>29/832</b>
<b>5</b>	<b>29/740; 29/832</b>	<b>29/832</b>
<b>6</b>	<b>29/739; 29/740; 29/743; 29/834; 29/836</b>	<b>29/832</b>
<b>7</b>		<b>29/832</b>
<b>8</b>	<b>257/E21.503; 257/E21.511; 29/740; 29/832</b>	<b>29/832</b>
<b>9</b>	<b>29/407.04; 29/714; 29/721; 29/743; 29/759; 29/832; 29/834</b>	<b>29/832</b>

	<b>Title</b>	<b>Current OR</b>
<b>10</b>	<b>Method of mounting an electronic part with bumps on a circuit board</b>	<b>174/261</b>
<b>11</b>	<b>Method and apparatus for mounting electronic parts</b>	<b>29/832</b>
<b>12</b>	<b>ELECTRONIC PART MOUNTING DEVICE</b>	
<b>13</b>	<b>ELECTRONIC PARTS MOUNTING ROBOT AND MOUNTING METHOD</b>	
<b>14</b>	<b>Automatic electronic parts mounting apparatus.</b>	
<b>15</b>	<b>Method and apparatus for mounting electronic device</b>	<b>29/832</b>
<b>16</b>	<b>Part mounter</b>	<b>29/832</b>
<b>17</b>	<b>Mounting apparatus of electronic parts and mounting methods of the same</b>	<b>29/832</b>
<b>18</b>	<b>Coil apparatus and manufacturing method for the same</b>	<b>29/606</b>
<b>19</b>	<b>CONDUCTIVE PASTE, CONDUCTIVE STRUCTURE USING THE SAME, ELECTRONIC PART, MODULE, CIRCUIT BOARD, METHOD FOR ELECTRICAL CONNECTION, METHOD FOR MANUFACTURING CIRCUIT BOARD, AND METHOD FOR MANUFACTURING CERAMIC ELECTRONIC PART</b>	<b>174/262</b>

	<b>Current XRef</b>	<b>Retrieval Classif</b>
<b>10</b>	<b>174/260; 174/266; 257/E21.511; 29/832; 29/833; 29/840; 361/760; 361/767; 361/768</b>	<b>29/832</b>
<b>11</b>	<b>29/714; 29/740; 29/743</b>	<b>29/832</b>
<b>12</b>	<b>29/832</b>	<b>29/832</b>
<b>13</b>	<b>29/832</b>	<b>29/832</b>
<b>14</b>	<b>29/832</b>	<b>29/832</b>
<b>15</b>	<b>29/739; 29/743</b>	<b>29/832</b>
<b>16</b>	<b>29/743</b>	<b>29/832</b>
<b>17</b>	<b>29/739; 29/740; 29/834</b>	<b>29/832</b>
<b>18</b>	<b>29/602.1; 29/832; 336/196; 361/760; 361/761</b>	<b>29/832</b>
<b>19</b>	<b>174/260; 174/264; 257/698; 257/E21.514; 29/832; 361/760; 361/779; 361/803; 428/313.5</b>	<b>29/832</b>

	<b>Title</b>	<b>Current OR</b>
<b>20</b>	<b>Process for fabricating a thin multi-layer circuit board</b>	<b>29/830</b>
<b>21</b>	<b>Apparatus and method for mounting electronic parts</b>	<b>156/299</b>
<b>22</b>	<b>Mounting structure of electric part and mounting method thereof</b>	<b>156/273.3</b>
<b>23</b>	<b>Parts distributing method</b>	<b>29/832</b>
<b>24</b>	<b>Method of mounting bumped electronic components</b>	<b>29/840</b>
<b>25</b>	<b>Substrate for mounting electronic part having conductive projections and process for manufacturing the same</b>	<b>174/52.4</b>
<b>26</b>	<b>Electronic parts supplying device and electronic parts mounting method</b>	<b>29/832</b>

	<b>Current XRef</b>	<b>Retrieval Classif</b>
<b>20</b>	<b>29/825; 29/832; 29/840</b>	<b>29/832</b>
<b>21</b>	<b>156/558; 156/559; 156/562; 156/563; 156/565; 221/270; 29/740; 29/832; 29/836; 414/798</b>	<b>29/832</b>
<b>22</b>	<b>156/275.7; 156/330; 257/781; 257/783; 29/832</b>	<b>29/832</b>
<b>23</b>	<b>29/740; 29/743</b>	<b>29/832</b>
<b>24</b>	<b>257/E21.503; 257/E21.511; 29/832; 29/846; 29/877; 29/878</b>	<b>29/832</b>
<b>25</b>	<b>174/260; 174/261; 257/E23.061; 257/E23.079; 257/E23.19; 29/832; 29/835; 361/764; 361/780; 361/783</b>	<b>29/832</b>
<b>26</b>	<b>29/740; 29/759; 29/834</b>	<b>29/832</b>

	<b>Title</b>	<b>Current OR</b>
<b>27</b>	<b>Mounting structure for electronic part</b>	<b>361/773</b>
<b>28</b>	<b>Electronic part mounting method</b>	<b>29/832</b>
<b>29</b>	<b>Electronic component layout determination method and a manufacturing method using the same</b>	<b>29/832</b>
<b>30</b>	<b>Facility operating method</b>	<b>700/101</b>
<b>31</b>	<b>Line of electronic part mounting apparatuses and method for mounting electronic parts</b>	<b>29/832</b>
<b>32</b>	<b>Electronic parts mounting method</b>	<b>29/832</b>
<b>33</b>	<b>Working apparatus</b>	<b>29/823</b>
<b>34</b>	<b>Method and apparatus for mounting electronic parts</b>	<b>29/832</b>
<b>35</b>	<b>METHOD FOR RECOGNIZING ELECTRONIC PART AND ELECTRONIC PART MOUNTING DEVICE THEREFOR</b>	

	<b>Current XRef</b>	<b>Retrieval Classif</b>
<b>27</b>	<b>257/696;</b> <b>257/723;</b> <b>257/726;</b> <b>257/E23.062;</b> <b>257/E23.068;</b> <b>257/E23.078;</b> <b>257/E25.022;</b> <b>257/E25.023;</b> <b>29/832;</b> <b>361/772;</b> <b>361/783</b>	<b>29/832</b>
<b>28</b>	<b>29/721;</b> <b>29/740;</b> <b>29/741;</b> <b>29/837</b>	<b>29/832</b>
<b>29</b>	<b>29/834;</b> <b>29/836</b>	<b>29/832</b>
<b>30</b>	<b>29/564.1;</b> <b>29/740;</b> <b>29/832;</b> <b>700/100;</b> <b>700/108;</b> <b>700/99</b>	<b>29/832</b>
<b>31</b>	<b>29/740;</b> <b>29/742;</b> <b>29/836</b>	<b>29/832</b>
<b>32</b>	<b>221/3;</b> <b>221/6;</b> <b>29/740;</b> <b>29/741;</b> <b>29/759</b>	<b>29/832</b>
<b>33</b>	<b>29/739;</b> <b>29/832</b>	<b>29/832</b>
<b>34</b>	<b>29/709;</b> <b>29/714</b>	<b>29/832</b>
<b>35</b>	<b>29/832</b>	<b>29/832</b>



	<b>Title</b>	<b>Current OR</b>
<b>36</b>	<b>METHOD FOR MOUNTING ELECTRONIC PARTS WITH ELECTRONIC PART MOUNTING MACHINE</b>	
<b>37</b>	<b>ELECTRONIC PARTS MOUNTING EQUIPMENT</b>	
<b>38</b>	<b>ELECTRONIC PART MOUNTING APPARATUS, PART ATTRACTING METHOD, AND PART MOUNTING METHOD</b>	
<b>39</b>	<b>ELECTRONIC PART MOUNING METHOD</b>	
<b>40</b>	<b>METHOD AND DEVICE FOR MOUNTING ELECTRONIC PARTS</b>	
<b>41</b>	<b>ELECTRONIC PART MOUNTING DEVICE</b>	
<b>42</b>	<b>ELECTRONIC PART MOUNTING JIG AND ELECTRONIC PART SOLDERING METHOD USING THE JIG</b>	
<b>43</b>	<b>ELECTRONIC PARTS MOUNTING METHOD</b>	
<b>44</b>	<b>ELECTRONIC PARTS MOUNTING METHOD</b>	
<b>45</b>	<b>ASSEMBLING METHOD FOR ELECTRONIC DEVICE</b>	
<b>46</b>	<b>MULTILAYER CIRCUIT BOARD</b>	
<b>47</b>	<b>MULTILAYER BOARD</b>	

	<b>Current XRef</b>	<b>Retrieval Classif</b>
<b>36</b>	<b>29/832</b>	<b>29/832</b>
<b>37</b>	<b>29/832</b>	<b>29/832</b>
<b>38</b>	<b>29/832</b>	<b>29/832</b>
<b>39</b>	<b>29/832</b>	<b>29/832</b>
<b>40</b>	<b>29/832</b>	<b>29/832</b>
<b>41</b>	<b>29/832</b>	<b>29/832</b>
<b>42</b>	<b>29/281.1; 29/832</b>	<b>29/832</b>
<b>43</b>	<b>29/832</b>	<b>29/832</b>
<b>44</b>	<b>29/832</b>	<b>29/832</b>
<b>45</b>	<b>29/739; 29/832</b>	<b>29/832</b>
<b>46</b>	<b>29/830; 29/832; 361/794</b>	<b>29/832</b>
<b>47</b>	<b>29/832</b>	<b>29/832</b>

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>56</b>	<b>"electronic parts mounting" and 29/740.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT</b>	<b>2003/05/23 07:54</b>
<b>2</b>	<b>19</b>	<b>("3279044"   "4515507"   "4606117"   "4794689"   "4807356"   "4860438"   "4951388"   "4979286"   "5058263"   "5060366"   "5070598"   "5136776"   "5255429"   "5290134"   "5421696"   "5491888"   "5544411"   "5864944"   "6000123").PN.</b>		<b>2003/05/23 07:51</b>
<b>3</b>	<b>7</b>	<b>("4881319"   "5060366"   "5223528"   "5323528"   "5383270"   "5437359"   "5500997").PN.</b>	<b>USPAT</b>	<b>2003/05/23 07:53</b>
<b>4</b>	<b>19</b>	<b>("3279044"   "4515507"   "4606117"   "4794689"   "4807356"   "4860438"   "4951388"   "4979286"   "5058263"   "5060366"   "5070598"   "5136776"   "5255429"   "5290134"   "5421696"   "5491888"   "5544411"   "5864944"   "6000123").PN.</b>	<b>USPAT</b>	<b>2003/05/23 07:54</b>
<b>5</b>	<b>47</b>	<b>"electronic parts mounting" and 29/832.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/05/23 07:57</b>
<b>6</b>	<b>45</b>	<b>"electronic parts mounting" and 29/743.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/05/23 08:09</b>
<b>7</b>	<b>19</b>	<b>("0661114"   "4670976"   "4794689"   "4951383"   "5135601"   "5235739"   "5294035"   "5323528"   "5390872"   "5419802"   "5553809"   "5628107"   "5784777"   "5809639"   "5840594"   "5855059"   "5860208"   "5873691"   "5894657").PN.</b>	<b>USPAT</b>	<b>2003/05/23 07:58</b>
<b>8</b>	<b>16</b>	<b>"electronic parts mounting" and 29/741.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/05/23 08:10</b>
<b>9</b>	<b>9</b>	<b>"electronic parts mounting" and 29/721.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/05/23 08:11</b>

10	8	"electronic parts mounting" and Munezane near Takashi .in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/23 08:12
-	1	"electronic parts mounting" and suction near section and 29/832.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:35
-	1	"electronic parts mounting" and Kawase near Takeyuki. inv. and Shimizu near Junkei .inv. and Uchiyama near Hiroshi .inv. and Yoshida near Noriaki. inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:50
-	1	"electronic parts mounting" and Kawase near Takeyuki. inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:50
-	246	"electronic parts mounting" and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:52
-	2	"electronic parts mounting" and 29/\$.ccls. and suction adj nozzle near section	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:56
-	47	"electronic parts mounting" and 29/832.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:05
-	13	"electronic parts mounting" and 29/833.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:13
-	2	("4914808"   "5018936").PN.	USPAT	2003/05/22 14:09
-	45	"electronic parts mounting" and 29/743.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:14
-	0	cleaver near tool and 29/33M.ccls. and 29/755.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:40

-	2	extraction near tool and 29/33M.ccls. and 29/755.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:41
-	1	extraction near tool and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:07
-	0	"cable stripping tool" and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:08
-	0	"stripping tool" and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:09
-	0	"optical fiber cleaver" and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:09
-	24	"optical fiber cleaver"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:11
-	261	optical adj fiber near tool	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:12
-	4	optical adj fiber near tool and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:18
-	7	("3674914"   "3769125"   "3960309"   "4450623"   "4693778"   "5259051"   "5292390").PN.	USPAT	2003/05/22 15:13
-	0	optical adj fiber near tool and 29/564.4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:19
-	80	tool and 29/564.4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:19